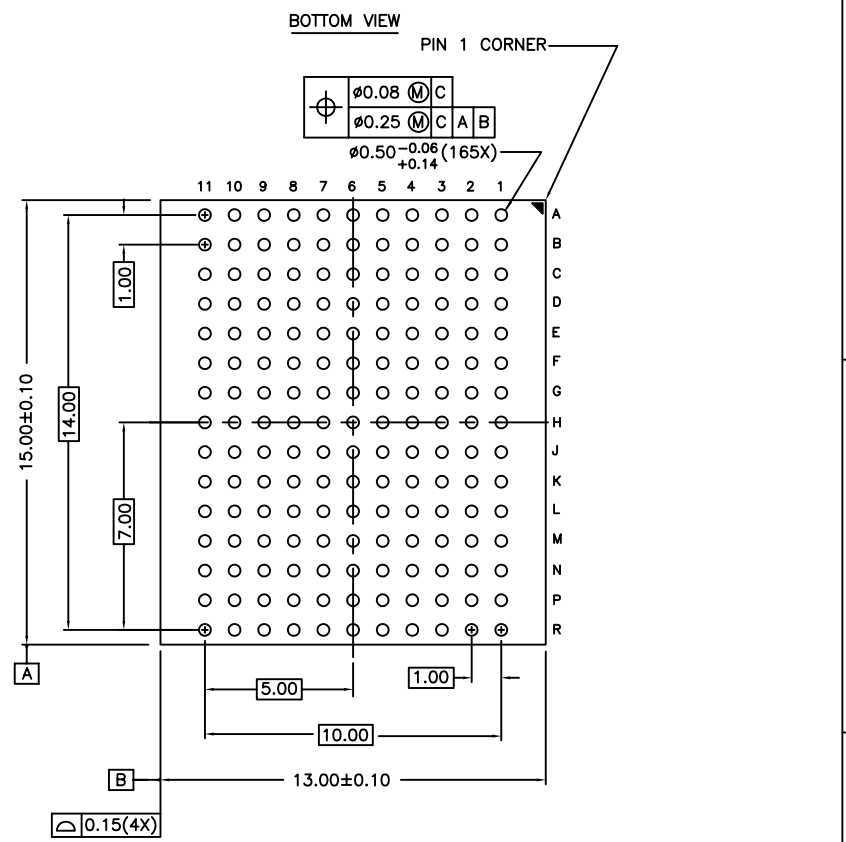


REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	124782	NEW RELEASE	02/21/03	N/A
1	-	*A	400534 2811236	CHANGE STANDOFF LIMIT FROM 0.41±0.05 TO 0.35±0.06 ADD SOLDER PAD TYPE AS NON SOLDER MASK DEFINED (NSMD) ADD PACKAGE WEIGHT 0.475g ADD JEDEC REFERENCE:MO-216/DESIGN 4.6C ADD PACKAGE CODE REFERENCE : BBOAC	05/18/04	N/A
1	A-5	*B	2741152	CONVERTED TO STANDARD DRAWING FORMAT CHANGED POSITION TOLERANCE FROM 0.05 TO 0.08	07/20/09	BZG
1	-	*C	2811236	Change Template and Title from PACKAGE OUTLINE, 165LD FBGA 13X15X1.40MM to PACKAGE OUTLINE, 165LD FBGA 13X15X1.4 MM BB165D/BW165D (0.5 BALL DIAMETER).	11/19/09	QAD
1	D-4	*D	3391562	Deleted PACKAGE WEIGHT : 0.475g	11/16/11	QAD
1	D-1	*E	3441910	ADD PACKAGE CODE BWOAC AND ADDED NOTE: PACKAGE WEIGHT: SEE CYPRESS PACKAGE MATERIAL DECLARATION DATASHEET (PMDD)	11/28/11	QAD
1	-	*F	3740180	NO CHANGE. SUNSET REVIEW.	09/11/12	QAD



NOTES :

- SOLDER PAD TYPE : NON-SOLDER MASK DEFINED (NSMD)
- JEDEC REFERENCE : MO-216 / ISSUE E
- PACKAGE CODE : BBOAC/BWOAC
- PACKAGE WEIGHT : SEE CYPRESS PACKAGE MATERIAL DECLARATION DATASHEET (PMDD) POSTED ON THE CYPRESS WEB.

THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°	DESIGNED BY TSV	DATE 07/20/09	 CYPRESS Company Confidential				
	DRAWN BY TZW/MP1	DATE 07/20/09					
	CHECKED BY BZG	DATE 07/20/09					
	APPROVED BY TZW	DATE 07/20/09					
MATERIAL N/A	APPROVED BY QAD	DATE 07/20/09	TITLE PACKAGE OUTLINE, 165LD FBGA 13X15X1.4 MM BB165D/BW165D (0.5 BALL DIAMETER)				
FINISH N/A	APPROVED BY CMG	DATE 07/20/09	<table border="1"> <tr> <td>SIZE A</td> <td>PART NO. BB165D/BW165D</td> <td>DWG NO. 51-85180</td> <td>REV *F</td> </tr> </table>	SIZE A	PART NO. BB165D/BW165D	DWG NO. 51-85180	REV *F
SIZE A	PART NO. BB165D/BW165D	DWG NO. 51-85180	REV *F				



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TITLE  
PACKAGE OUTLINE, 165LD FBGA 13X15X1.4 MM BB165D/BW165D (0.5 BALL DIAMETER)

SIZE A	PART NO. BB165D/BW165D	DWG NO. 51-85180	REV *F
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SCALED TO FIT N/A SHEET 1 OF 1